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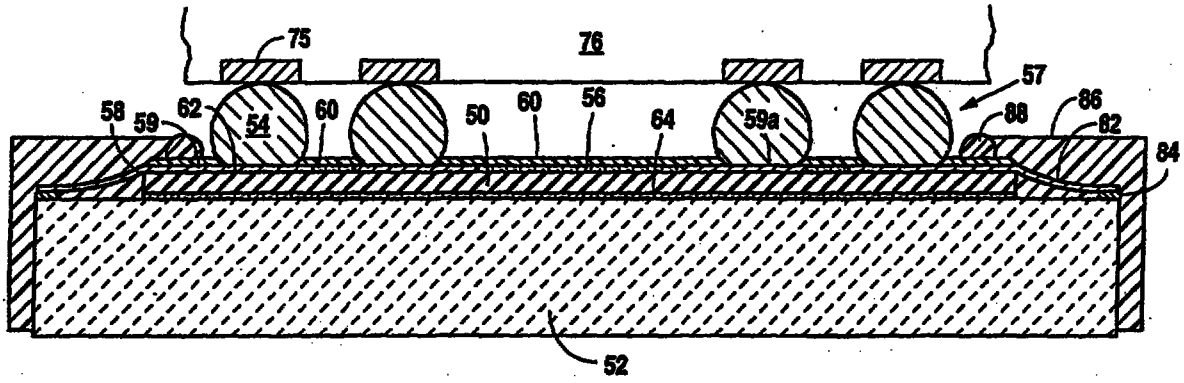
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(54) Title: CHIP SCALE BALL GRID ARRAY FOR INTEGRATED CIRCUIT PACKAGE



(57) Abstract

A chip scale ball grid array for integrated circuit packaging having a nonpolymer layer (50) or support structure positioned between a semiconductor die (52) and a substrate (76). The nonpolymer support structure acts to increase circuit reliability by reducing thermal stress effects and/or by reducing or eliminating formation of voids in an integrated circuit package. A nonpolymer support structure may be a material, such as copper foil, having sufficient rigidity to allow processing of chip scale package in strip format.